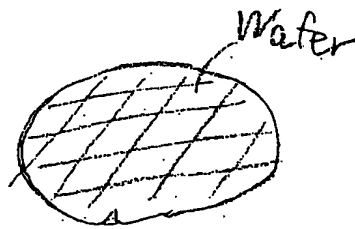


Process flow of Flip Chip interconnection.

Fig. 1A



Cross Section of electrode-pad

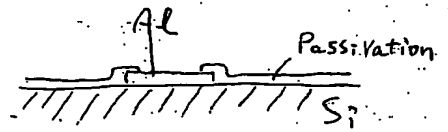


Fig. 1B UBM forming
(Under Bump Metals)

UBM is formed by
sputtering or plating.

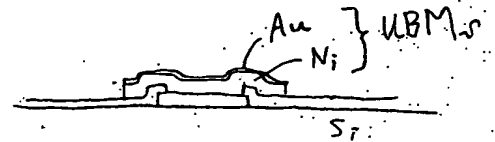


Fig. 1C Solder Bump forming

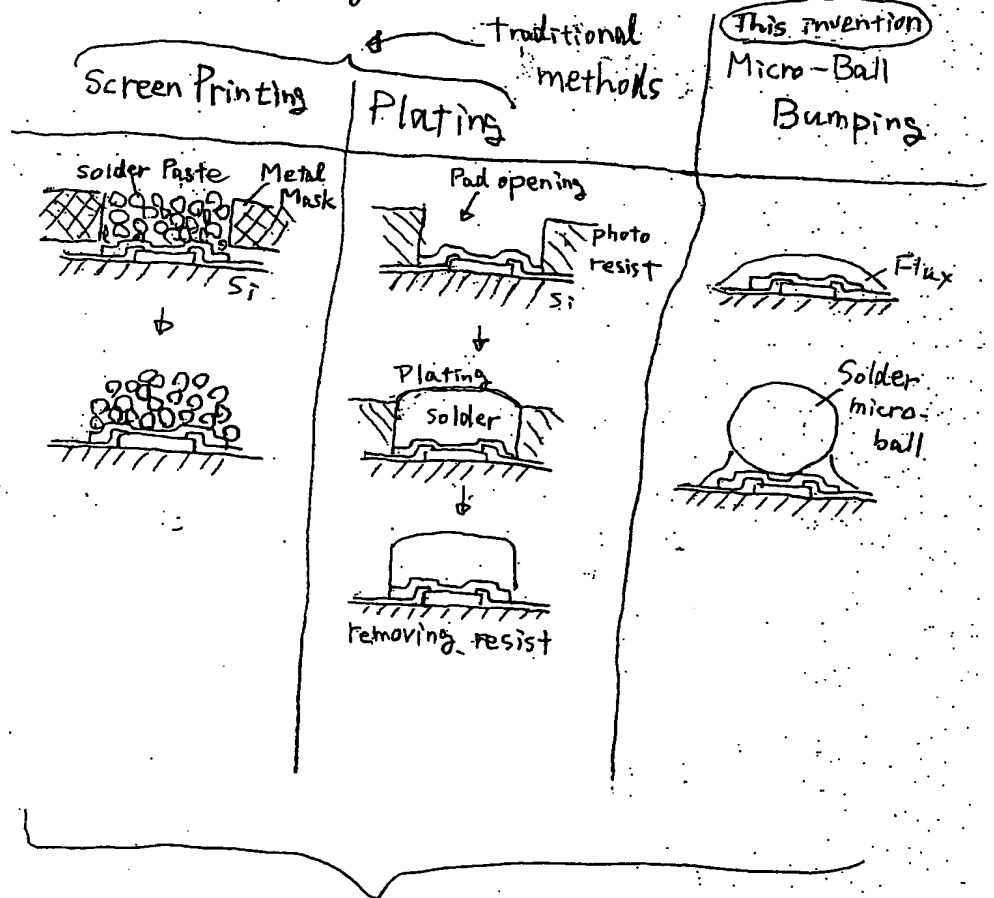
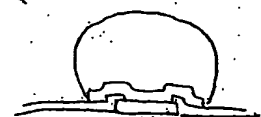


Fig. 1D Reflow



Complete

Fig. 1E Dicing

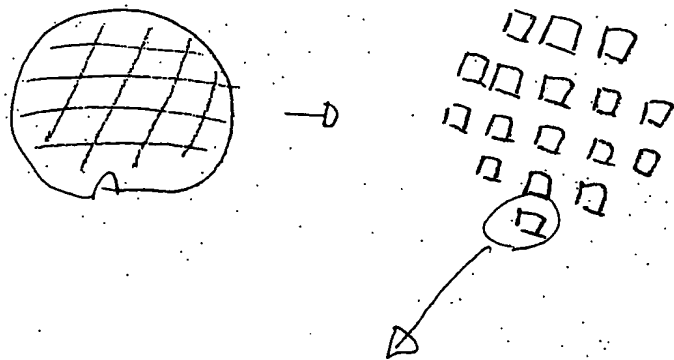


Fig. 1F Flip Chip Bonding

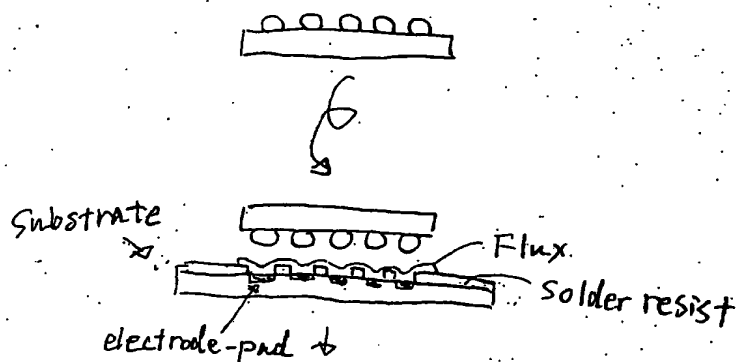


Fig. 1G Reflow and Cleaning

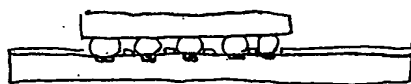


Fig. 1H

